

Absolute Maximum Ratings

(Ta=25°C, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-source Voltage	V _{DSS}	400	V
Drain-Gate Voltage (R _{GS} =1MΩ)	V _{DGR}	400	V
Gate-Source (GND) Voltage	V _{GS}	±30	V
Drain Current Pulsed ⁽²⁾	I _{DM}	18.4	ADC
Single Pulsed Avalanch Current ⁽³⁾ (Energy ⁽²⁾)	I _{AS} (EAS)	20(360)	A(mJ)
Continuous Drain Current (T _c = 25°C)	I _D	4.6	ADC
Continuous Drain Current (T _C =100°C)	I _D	2.9	ADC
Supply Voltage	V _{CC}	40	V
Analog Input Voltage Range	V _{sync}	-0.3 to 13V	V
	V _{FB}	-0.3 to V _{CC}	V
Total Power Dissipation	P _D	42	W
	Derating	0.33	W/°C
Operating Junction Temperature	T _J	+160	°C
Operating Ambient Temperature	T _A	-25 to +85	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C
Thermal Resistance	R _{thjc}	2.98	°C/W
ESD Capability, HBM Model (All pins)	-	2.0	kV
ESD Capability, Machine Model (All pins)	-	300	V

Notes:

1. T_j = 25°C to 150°C
2. Repetitive rating: Pulse width limited by maximum junction temperature
3. L = 30mH, V_{DD} = 50V, R_G = 25Ω, starting T_j = 25°C
4. L = 13uH, starting T_j = 25°C

Electrical Characteristics (SFET Part)

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 50μA	400	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = Max, Rating, V _{GS} = 0V	-	-	200	μA
		V _{DS} = 0.8*Max., Rating V _{GS} = 0V, T _C = 85°C	-	-	300	μA
Static Drain-source on Resistance ^(Note)	R _{DS(ON)}	V _{GS} = 10V, I _D = 2.3A	-	0.9	1.1	Ω
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	-	710	-	pF
Output Capacitance	C _{oss}		-	90	-	
Reverse Transfer Capacitance	C _{rss}		-	10	-	
Turn on Delay Time	t _{d(on)}	V _{DD} = 0.5BV _{DSS} , I _D = 7.0A (MOSFET switching time are essentially independent of operating temperature)	-	15	-	nS
Rise Time	t _r		-	55	-	
Turn Off Delay Time	t _{d(off)}		-	55	-	
Fall Time	t _f		-	50	-	
Total Gate Charge (Gate-Source+Gate-Drain)	Q _g	V _{GS} = 10V, I _D = 7.0A, V _{DS} = 0.5B V _{DSS} (MOSFET Switching time are Essentially independent of operating temperature)	-	20	26	nC
Gate-Source Charge	Q _{gs}		-	4.0	-	
Gate-Drain (Miller) Charge	Q _{gd}		-	7.3	-	

Note:

1. Pulse test : Pulse width ≤ 300μS, duty ≤ 2%

Electrical Characteristics (Continued)

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
UVLO SECTION						
Start Threshold Voltage	VSTART	VFB = GND	14	15	16	V
Stop Threshold Voltage	VSTOP	VFB = GND	8	9	10	V
OSCILLATOR SECTION						
Initial Frequency	FOSC	-	18	20	22	kHz
Voltage Stability	FSTABLE	12V ≤ Vcc ≤ 23V	0	1	3	%
Temperature Stability (Note2)	ΔFOSC	-25°C ≤ Ta ≤ 85°C	0	±5	±10	%
Maximum Duty Cycle	DMAX	-	92	95	98	%
Minimum Duty Cycle	DMIN	-	-	-	0	%
FEEDBACK SECTION						
Feedback Source Current	IFB	VFB = GND	0.7	0.9	1.1	mA
Shutdown Feedback Voltage	VSD	Vfb ≥ 6.9V	6.9	7.5	8.1	V
Shutdown Delay Current	IDELAY	VFB = 5V	4	5	6	μA
PROTECTION SECTION						
Over Voltage Protection	VOVP	Vsync ≥ 11V	11	12	13	V
Over Current Latch Voltage (Note2)	VOCL	-	0.9	1.0	1.1	V
Thermal Shutdown Temp.	TSD	-	140	160	-	°C

Note:

1. These parameters is the current flowing in the Control IC.
2. These parameters, although guaranteed, are tested in EDS(wafer test) process.
3. These parameters indicate Inductor Current.

Electrical Characteristics (Continued)

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
SYNC SECTION						
Normal Sync High Threshold Voltage	VNSH	Vcc = 16V, Vfb = 5V	4.0	4.6	5.2	V
Normal Sync Low Threshold Voltage	VNSL	Vcc = 16V, Vfb = 5V	2.3	2.6	2.9	V
Burst Sync High Threshold Voltage	VBSH	Vcc = 10.5V, Vfb = 0V	3.2	3.6	4.0	V
Burst Sync Low Threshold Voltage	VBSL	Vcc = 10.5V, Vfb = 0V	1.1	1.3	1.5	V
BURST MODE SECTION						
Burst mode Low Threshold Voltage	VBURL	Vfb = 0V	10.4	11.0	11.6	V
Burst mode High Threshold Voltage	VBURH	Vfb = 0V	11.4	12.0	12.6	V
Burst mode Enable Feedback Voltage	VBEN	Vcc = 10.5V	0.7	1.0	1.3	V
Burst mode Peak Current Limit	IBU_PK	Vcc = 10.5V	0.65	0.85	1.1	A
PRIMARY SIDE REGULATION SECTION						
Primary Regulation Threshold Voltage	VPR	I _{fb} = 700uA, Vfb = 4V	32.0	32.5	33.0	V
Primary Regulation Transconductance	GPR	-	2.0	2.6	-	mA/V
CURRENT LIMIT(SELF-PROTECTION)SECTION						
Peak Current Limit(Note3)	IPK	-	4.4	5.0	5.6	A
TOTAL DEVICE SECTION						
Start Up Current	ISTART	Vfb = GND, VCC = 14V	-	0.1	0.2	mA
Operating Supply Current (Note1)	IOP	Vfb = GND, VCC = 16V	-	10	18	mA
	IOP(MIN)	Vfb = GND, VCC = 10V				
	IOP(MAX)	Vfb = GND, VCC = 28V				

Note:

1. These parameters is the current flowing in the Control IC.
2. These parameters, although guaranteed, are tested in EDS(wafer test) process.
3. These parameters indicate Inductor Current.

Typical Performance Characteristics

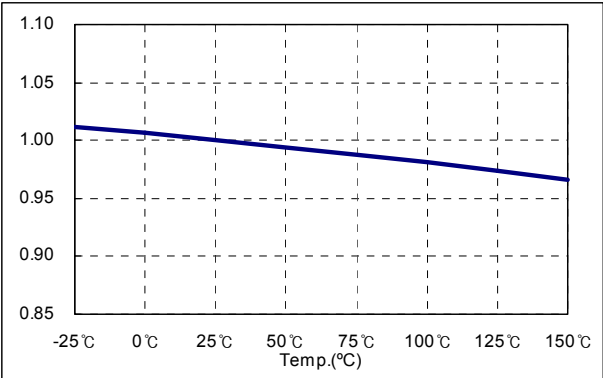


Figure 1. Start Voltage

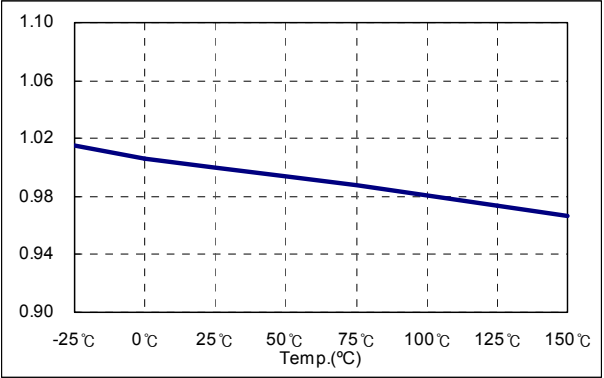


Figure 2. Stop Voltage

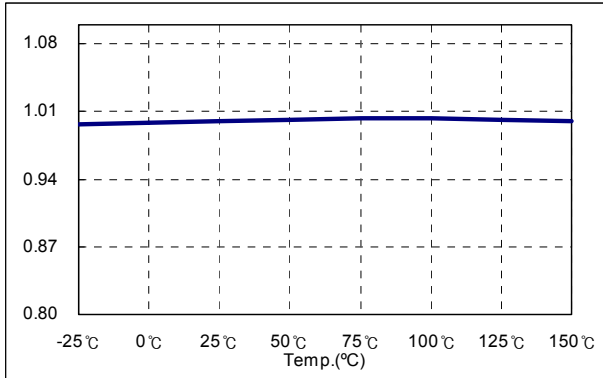


Figure 3. Stand by Current

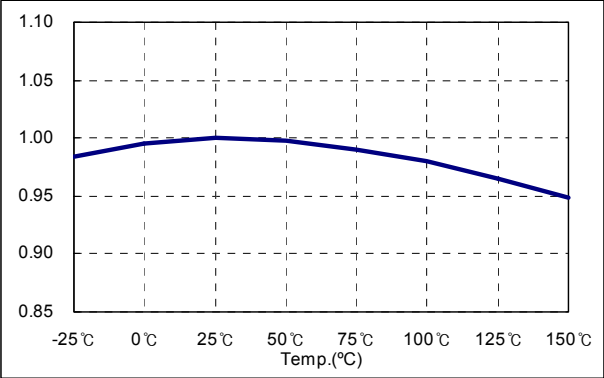


Figure 4. Operating Current

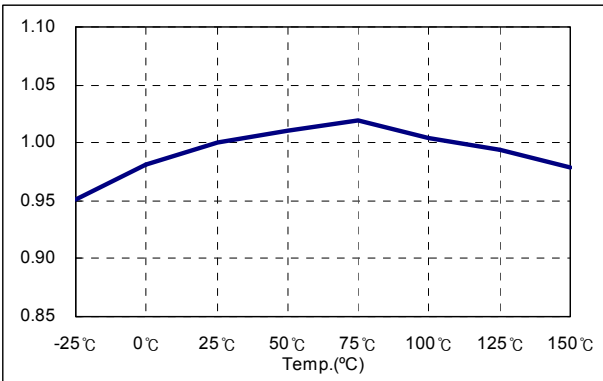


Figure 5. Initial Frequency

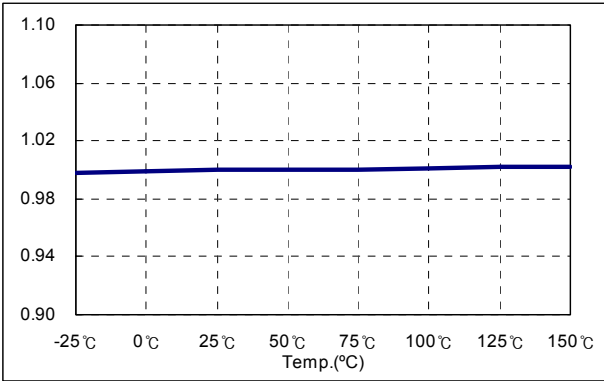


Figure 6. Maximum Duty

Typical Performance Characteristics (Continued)

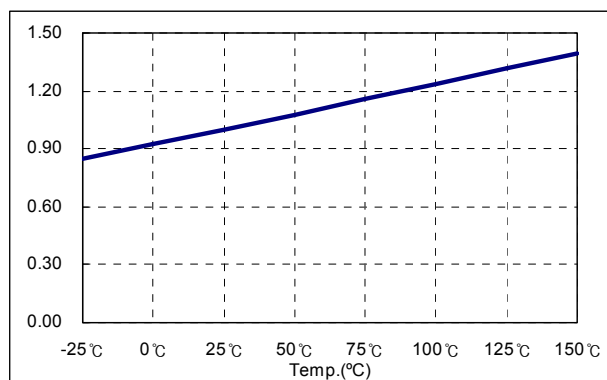


Figure 7. Feedback Offset Voltage

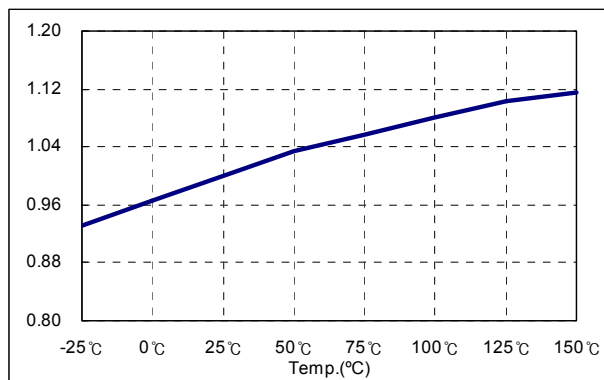


Figure 8. Feedback Source Current

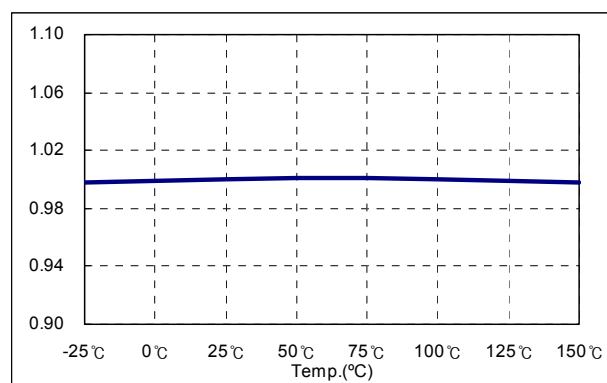


Figure 9. Over Voltage Protection

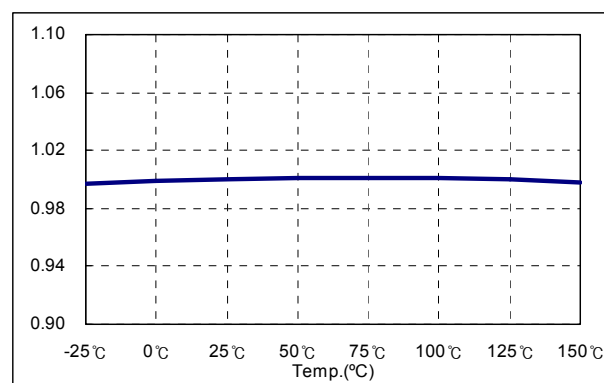


Figure 10. Shutdown Feedback Voltage

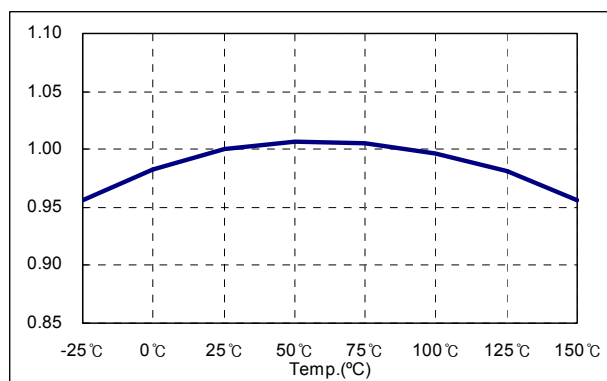


Figure 11. ShutDown Delay Current

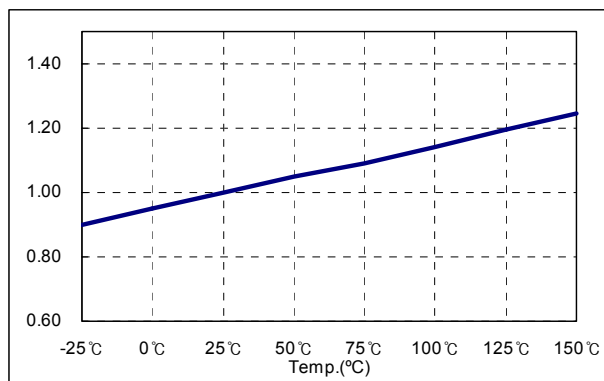


Figure 12. Burst Mode Enable Feedback Voltage

Typical Performance Characteristics (Continued)

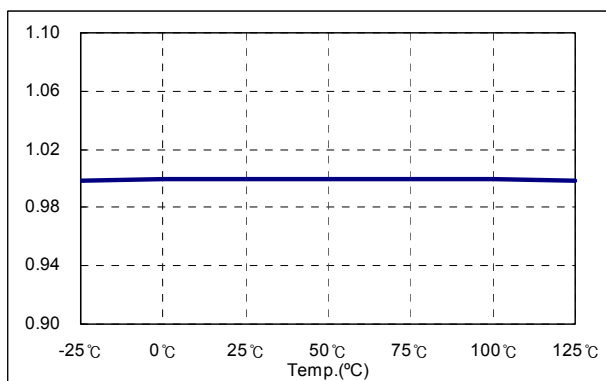


Figure 13. Burst Mode Low Threshold Voltage

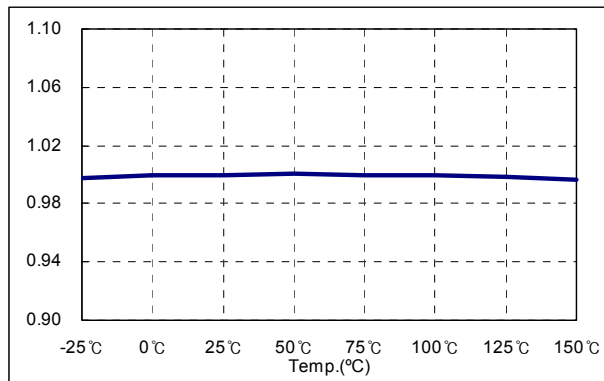


Figure 14. Burst Mode High Threshold Voltage

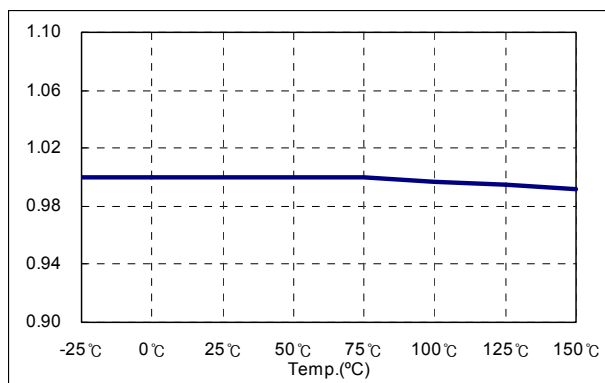


Figure 15. Burst Mode Sync. High Threshold Voltage

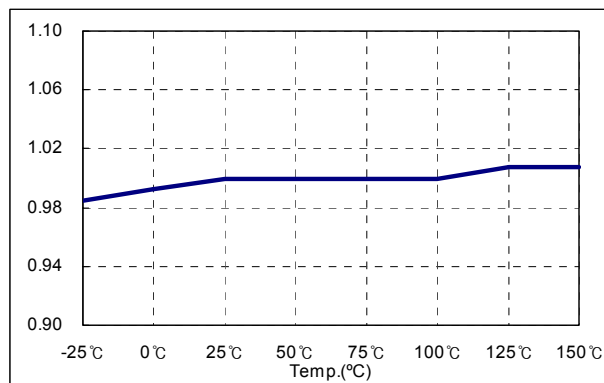


Figure 16. Burst Mode Sync. Low Threshold Voltage

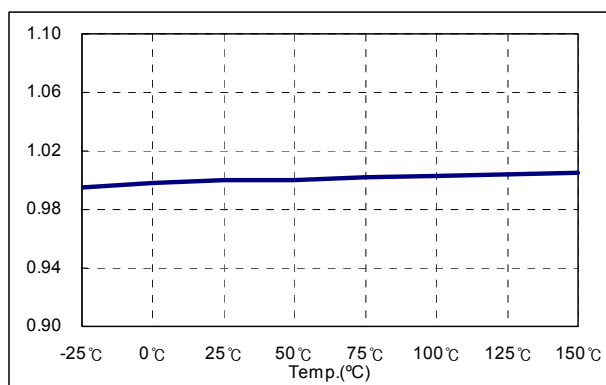


Figure 17. Primary Voltage

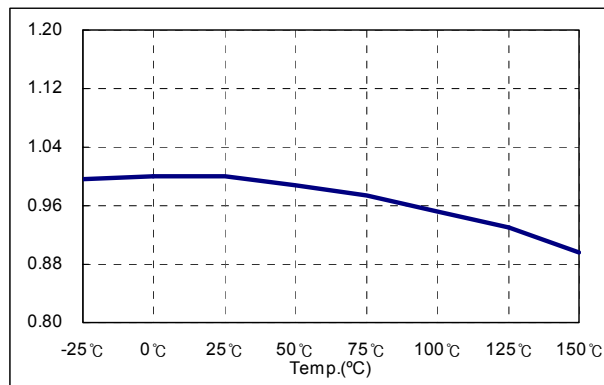


Figure 18. Primary Mode Gain

Typical Performance Characteristics (Continued)

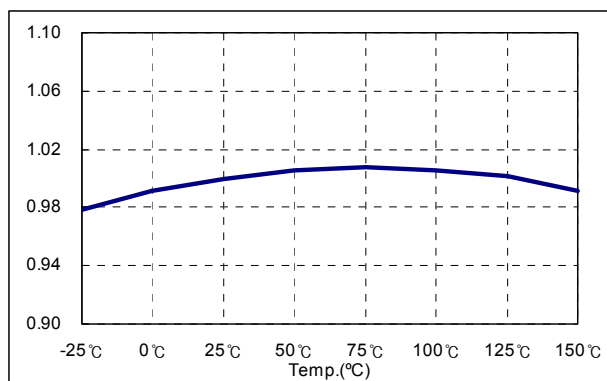


Figure 19. Peak Current Limit

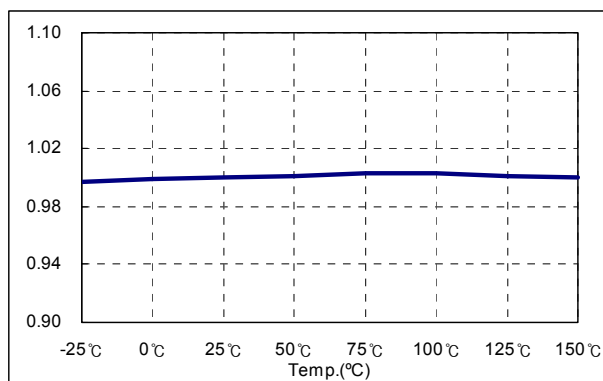


Figure 20. Burst Mode Peak Current Limit

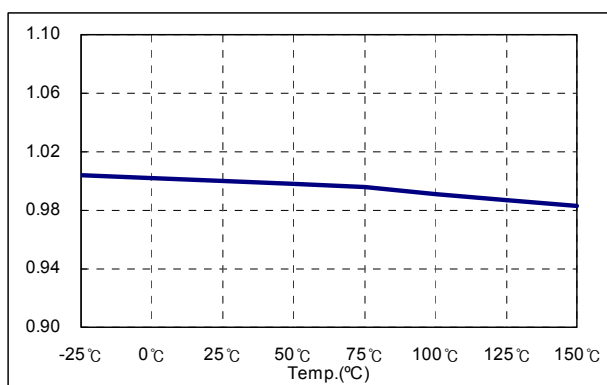


Figure 21. Normal Mode Sync. High Threshold Voltage

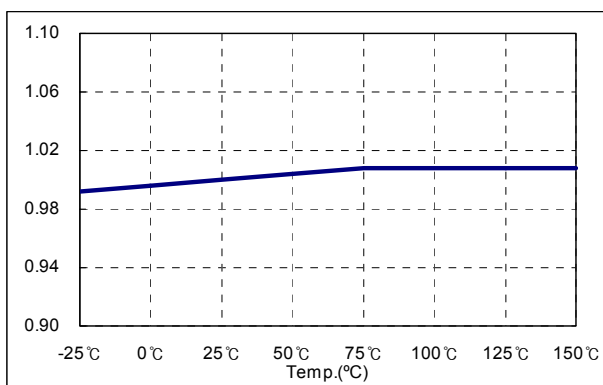


Figure 21. Normal Mode Sync. Low Threshold Voltage

Typical Performance Characteristics(MOSFET Part)

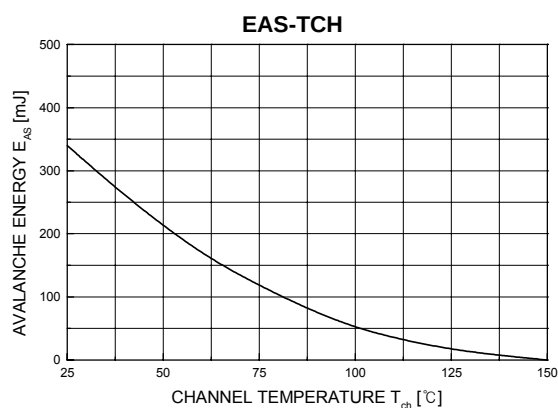


Figure 22. Temperature (T_C) vs. Eas Curve

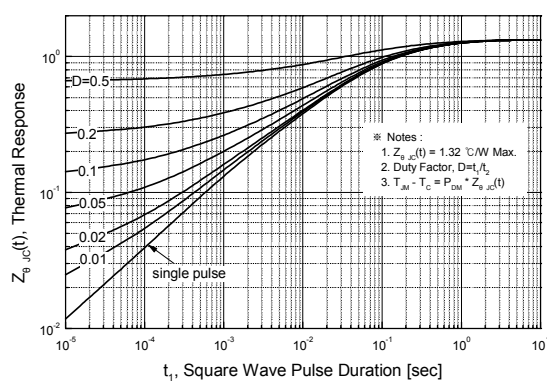
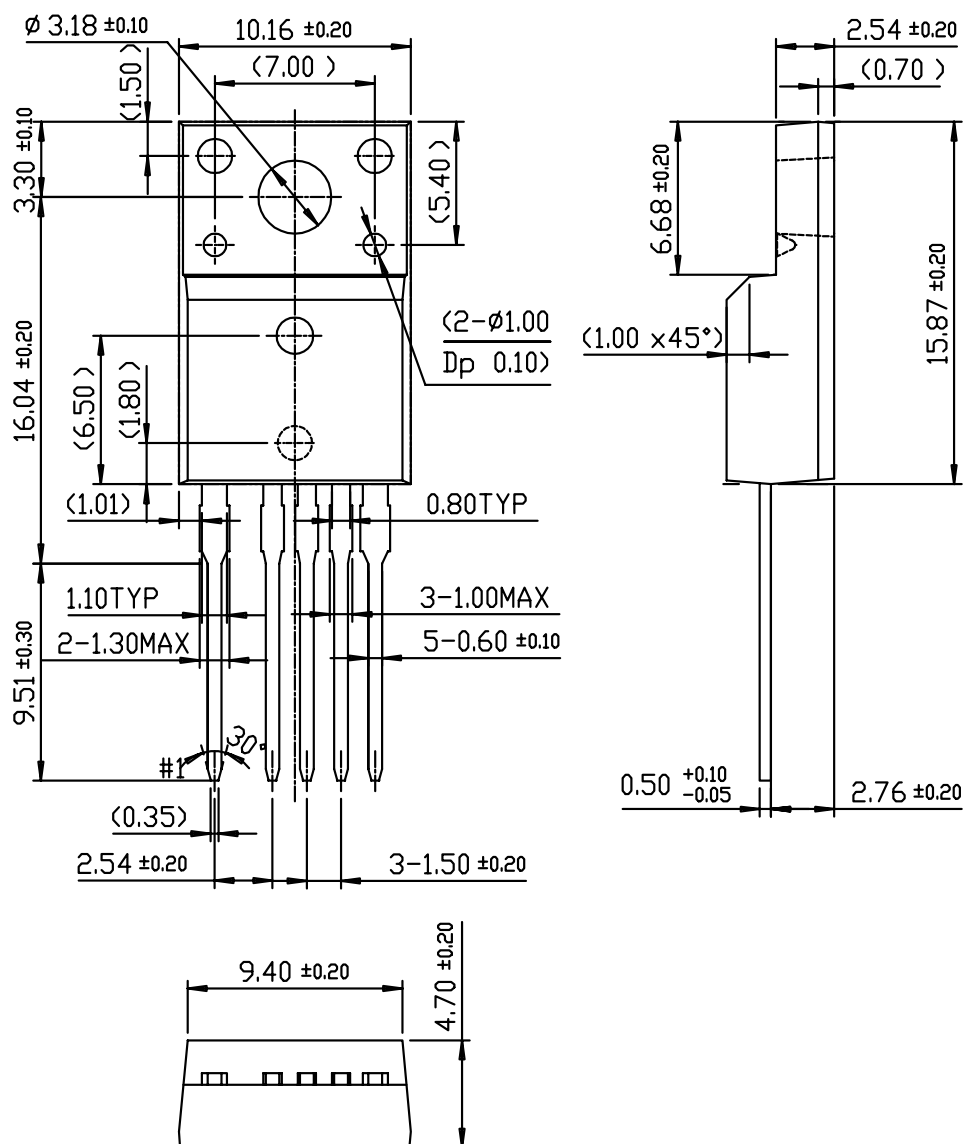


Figure 23. Transient Thermal Response Curve

Package Dimensions

TO-220F-5L



Technical drawing of a connector assembly showing three views: front, side, and top.

Front View Dimensions:

- Overall Width: 10.16 ± 0.20
- Overall Height: 15.87 ± 0.20
- Top Flange Width: $\phi 3.18 \pm 0.10$
- Top Flange Thickness: 1.10 TYP
- Top Flange Hole Diameter: $(2 - \phi 1.00)$
- Top Flange Hole Pitch: $(D_p 0.10)$
- Top Flange Hole Position: (7.00)
- Top Flange Hole Diameter: (1.50)
- Top Flange Hole Position: (5.40)
- Top Flange Hole Diameter: (6.50)
- Top Flange Hole Position: (1.80)
- Top Flange Hole Diameter: (1.01)
- Top Flange Hole Position: $2-1.30 \text{ MAX}$
- Top Flange Hole Position: $(\#1, \#5)$
- Top Flange Hole Position: $3-1.00 \text{ MAX}$
- Top Flange Hole Position: $(\#2, \#3, \#4)$
- Top Flange Hole Position: 0.80 TYP
- Top Flange Hole Position: $3-1.50 \text{ TYP}$
- Top Flange Hole Position: $[3-1.50 \pm 0.20]$
- Top Flange Hole Position: 2.54 TYP
- Top Flange Hole Position: $[2.54 \pm 0.20]$
- Top Flange Hole Position: $5-0.60 \pm 0.10$

Side View Dimensions:

- Overall Height: 18.20 ± 0.50
- Base Width: 3.18 ± 0.30
- Base Thickness: $0.50^{+0.10}_{-0.05}$
- Base Hole Diameter: $(\#1, \#3, \#5)$
- Base Hole Position: 2.76 ± 0.30
- Base Hole Position: $(\#2, \#4)$
- Base Hole Position: 5.00 ± 0.50
- Base Hole Position: 5.63 ± 0.50
- Base Hole Position: 16.08
- Base Hole Position: (3.50)
- Base Hole Position: 6.68 ± 0.20
- Base Hole Position: 2.54 ± 0.20
- Base Hole Position: (0.70)
- Base Hole Position: $(1.00 \times 45^\circ)$

Top View Dimensions:

- Overall Width: 9.40 ± 0.20
- Overall Height: 4.70 ± 0.20

Ordering Information

Product Number	Package	Operating Temp.
KA5Q0740RTTU	TO-220F-5L	-25°C to +85°C
KA5Q0740RTYDTU	TO-220F-5L(Forming)	

TU : Non Forming Type

YDTU : Forming Type

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.